

ABSTRACT

A high-frequency module having a communication function is provided which includes a base substrate block (2) formed from organic substrates (11, 12), the organic substrate (11) having wiring layers (14, 15) formed on main sides, respectively, thereof while the organic substrate (12) has wiring layers (16, 17) formed on main sides, respectively, thereof, the base substrate block (2) having a buildup surface formed by flattening an uppermost layer, and an elements block (3) formed from organic insulative layers (26, 28) formed on the buildup surface of the base substrate block (2) and in which a plurality of conductive parts (19, 20, 32) forming passive elements and distributed parameter elements, which transmit a high-frequency signal, are formed along with wiring layers (27, 29). The conductive parts (19, 20, 32) in the elements block (3) are formed correspondingly to portions of the organic substrate (11) in the base substrate block (2) where no woven glass fabric is laid.